

U.S. Patent Application Serial No. 10/777,039
Amendment filed February 24, 2005
Supplemental Amendment to OA dated November 4, 2004

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1. (Currently Amended): A chip-on-film use copper foil comprising a copper foil on at least one surface of which is provided an alloy fine roughening particle layer comprised of a copper-cobalt-nickel alloy with contents of cobalt and nickel equal to or greater than that of copper, wherein the amount ratio of copper-cobalt-nickel is 1 : 1.2 to 2.2 : 1.0 to 2.0.

Claim 2. (Original): A chip-on-film use copper foil as set forth in claim 1, wherein said alloy fine roughening particle layer provided on said copper foil surface is treated for stainproof.

Claim 3. (Original): A chip-on-film use copper foil as set forth in claim 1, wherein said alloy fine roughening particle layer provided on said copper foil surface is treated by a silane coupling agent.

U.S. Patent Application Serial No. 10/777,039
Amendment filed February 24, 2005
Supplemental Amendment to OA dated November 4, 2004

Claim 4. (New): A chip-on-film use copper foil comprising a copper foil on at least one surface of which is provided an alloy fine roughening particle layer comprised of a copper-cobalt-nickel alloy with contents of cobalt and nickel equal to or greater than that of copper, the copper foil being bonded to a substrate.